

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDF915AN-F11 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ DATE 日期: \_\_\_\_\_ 2006-5-11 \_\_\_\_\_

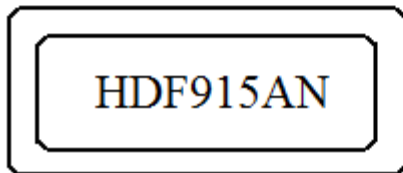
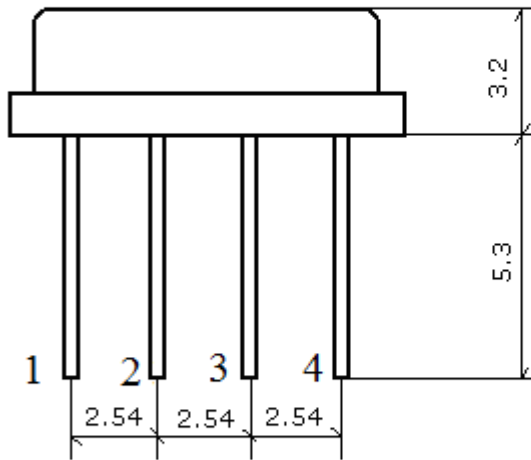
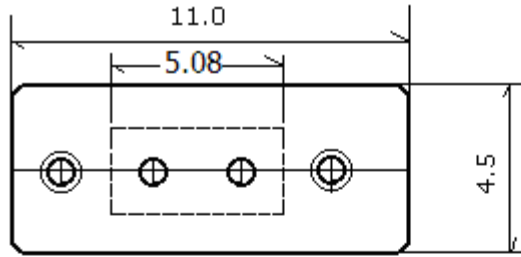
客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司  
Shoulder Electronics Limited

## 更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

## 1. Package Dimension



### Pin configuration

- 1. Input
- 4. Output
- 2,3 Ground

## 2. Marking: HDF915AN

## 3. Performance

### 3.1 Application

Low-Loss SAW Filter of cordless system.

Center Frequency: 915 MHz

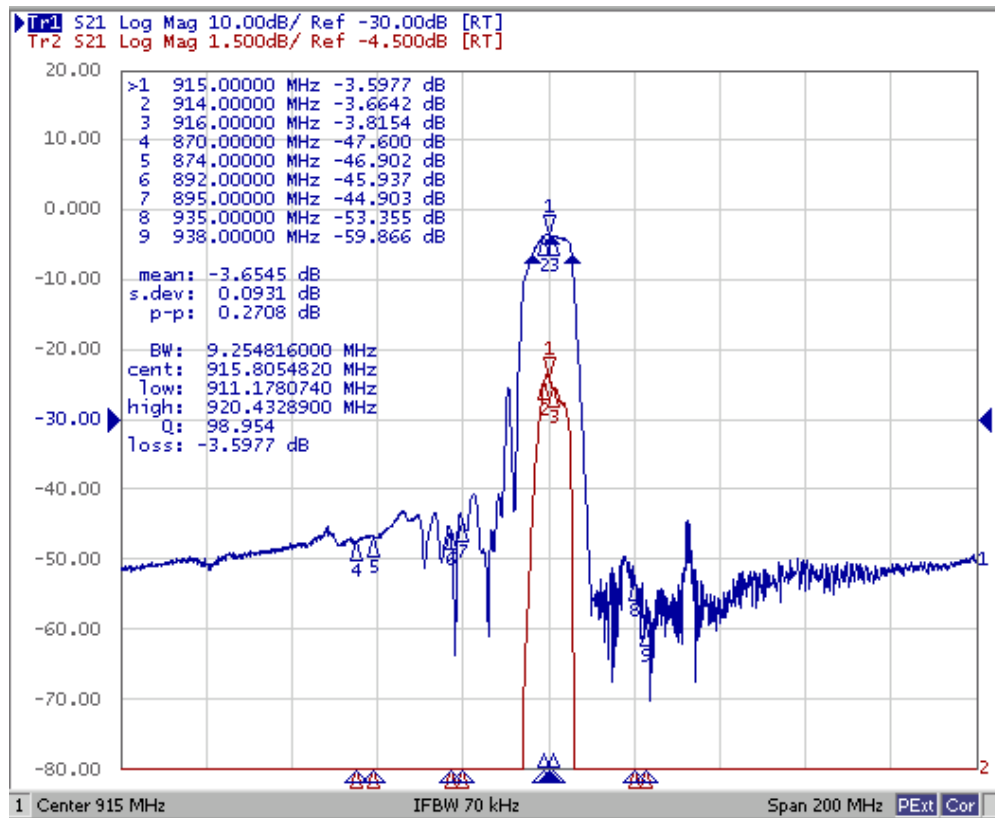
### 3.2 Maximum Rating

Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-40°C to +85°C
DC. Permissive Voltage	0 V DC. max.
Maximum Input Power	10dBm

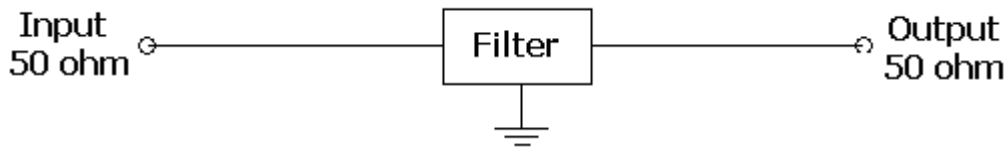
### 3.3 Electronic Characteristics

Item	Specification
Center Frequency(fo)	915 MHz
Insertion Loss(dB)	
1.)914-916 MHz	4.5max
2.)870-874 MHz	40 min
3.)892-895MHz	30 min
4.)935-938MHz	30 min
5.)956-961 MHz	40 min
Ripple deviation (914-916MHz)(dB)	1.5max
Input/output Impedance(Nominal)	50Ω

### 3.4 Frequency Characteristics



### 3.5 Test Circuit



## 4. ENVIRONMENTAL CHARACTERISTICS

### 4-1 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}\text{C}$  for 30 minutes. Following by a high temperature of  $+25^{\circ}\text{C}$  for 5 Minutes and a higher temperature of  $+85^{\circ}\text{C}$  for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 3.3.

### 4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10 \pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 3.3.

### 4-3 Solderability

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 3.3.

### 4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 3.3.

### 4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 3.3.

## 5. REMARK

### 5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.